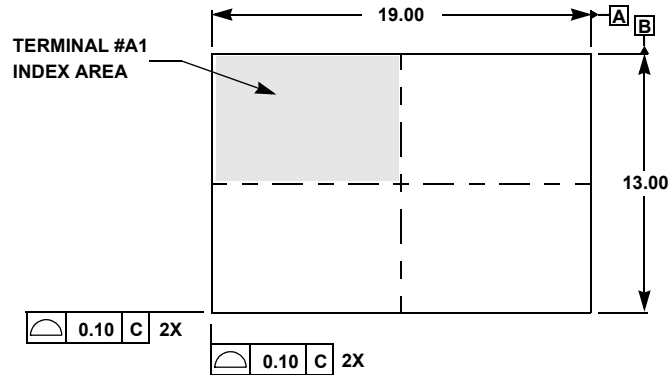


Package Outline Drawing

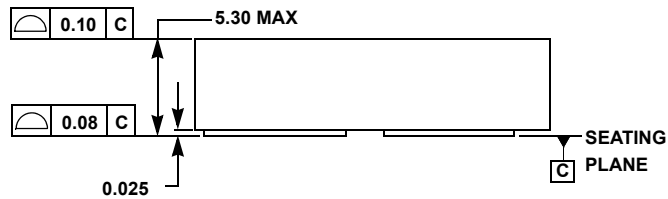
Y22.19x13

22 I/O 19mmx13mmx5.30mm HDA MODULE

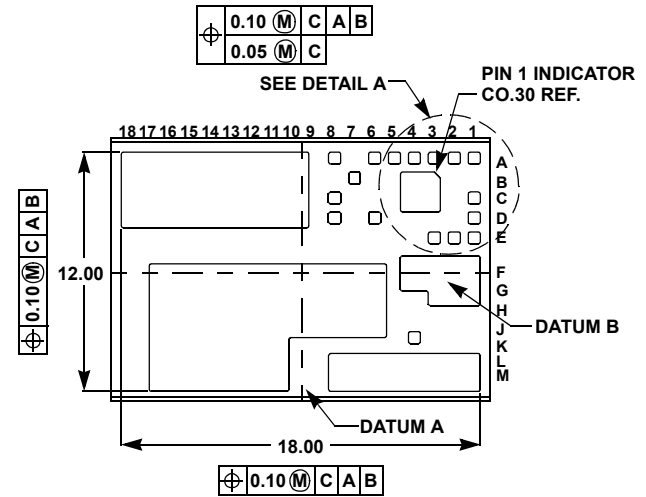
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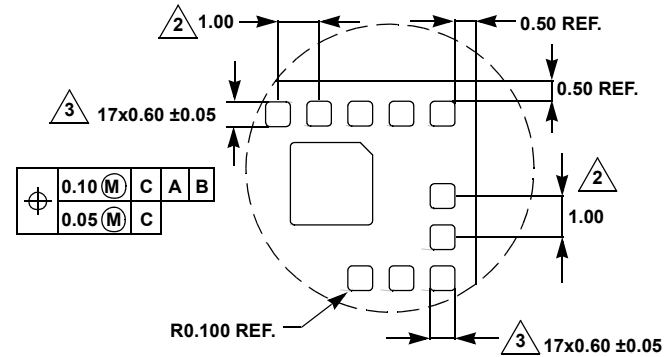
TOP VIEW



SIDE VIEW



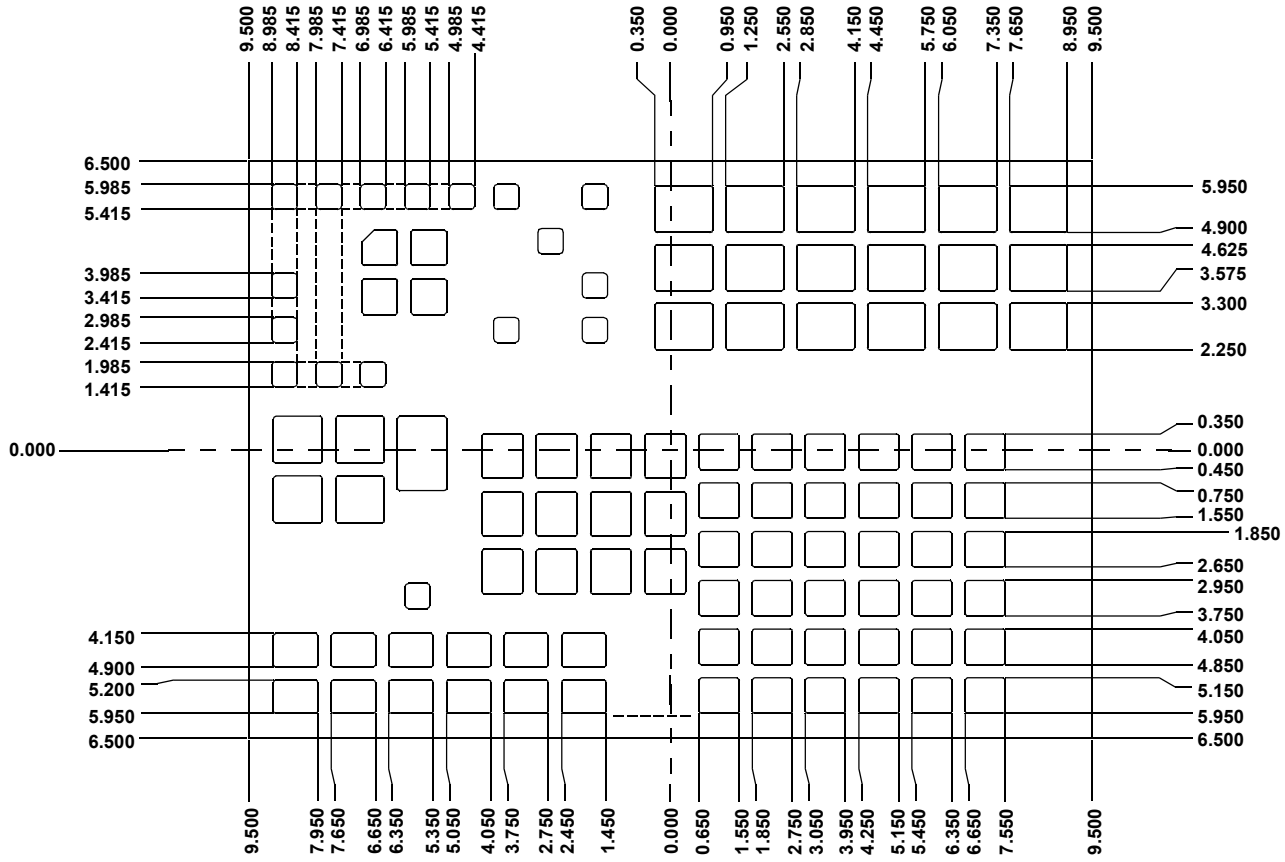
BOTTOM VIEW



**DETAIL A
(SCALE 2:1)**

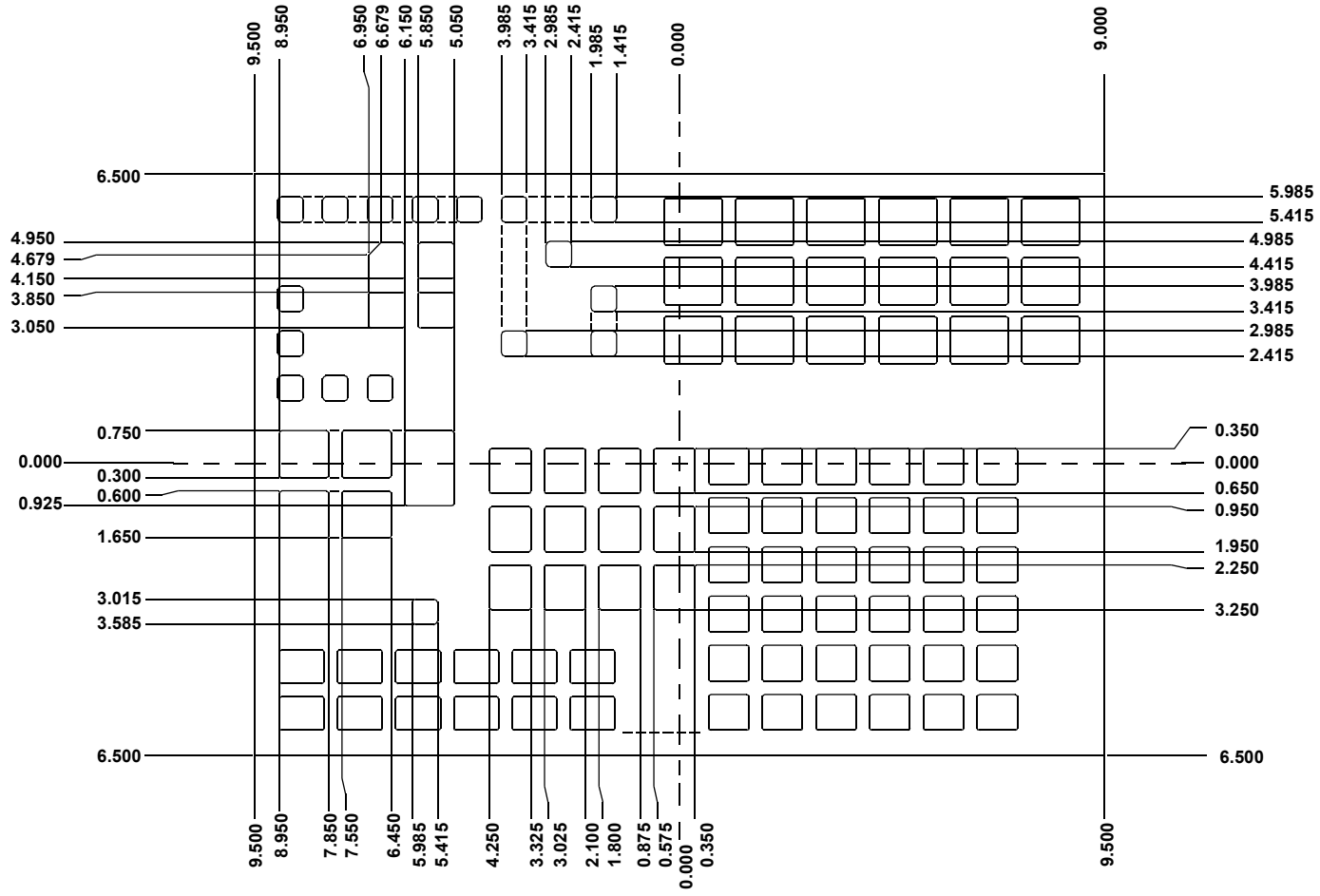
NOTES:

1. All dimensions are in millimeters.
2. Represents the basic land grid pitch.
3. These 17 I/Os are centered in a fixed row and column matrix at 1.0mm pitch BSC.
4. Dimensioning and tolerancing per ASME Y14.5-2009.
5. Tolerance for exposed PAD edge location dimension is ± 0.1 mm.

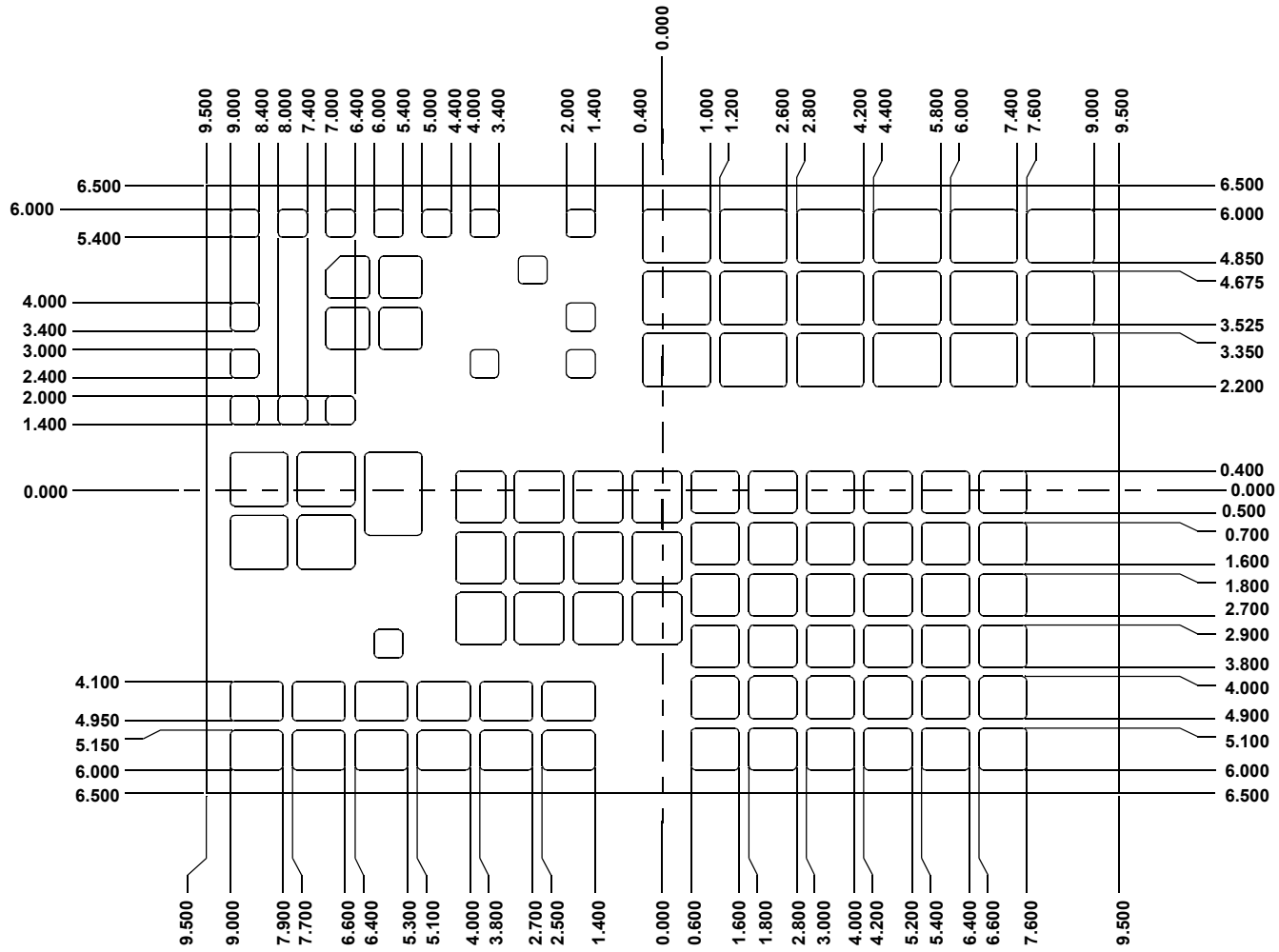


RECOMMENDED SOLDER STENCIL

TOP VIEW 1

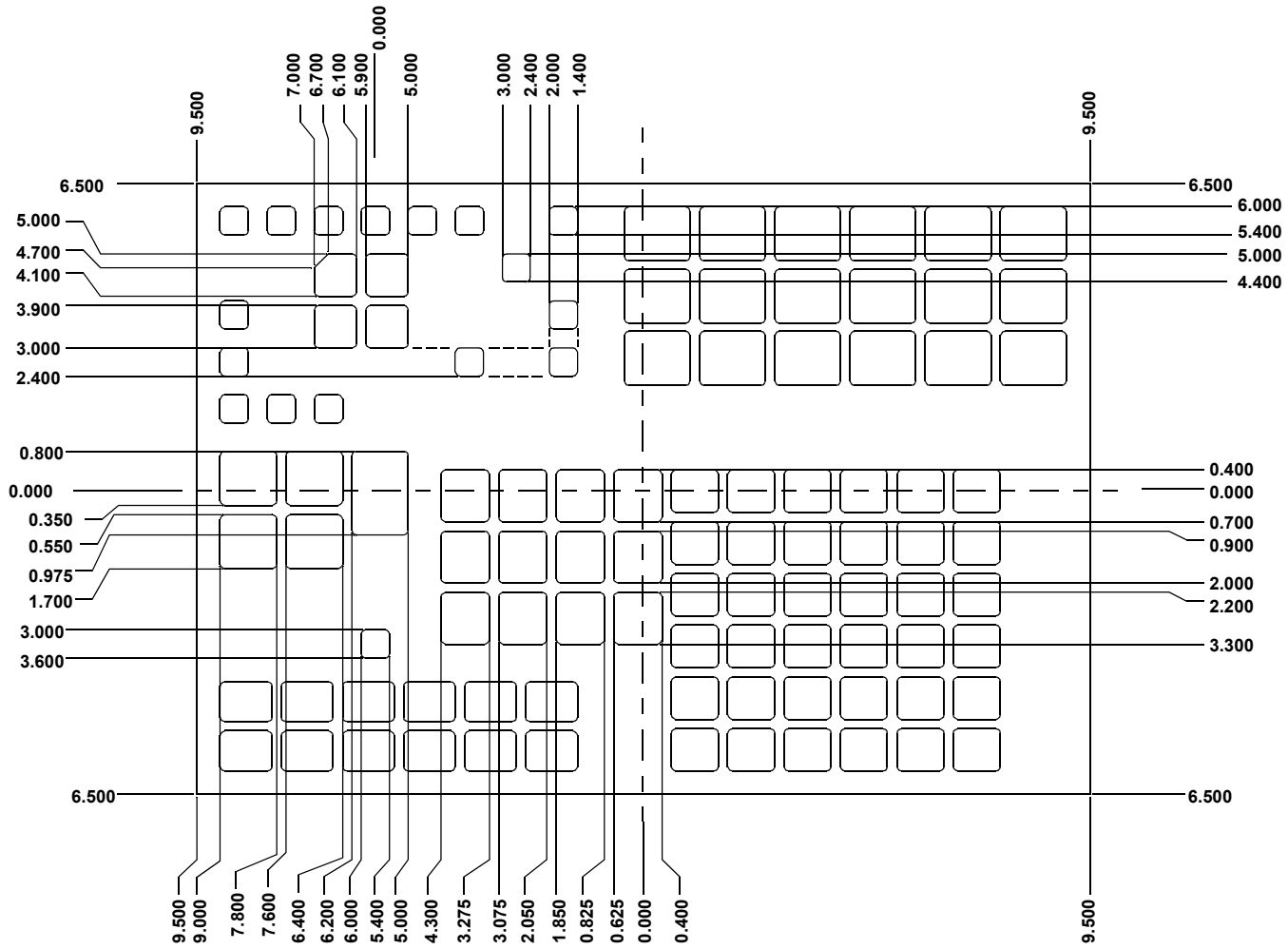


RECOMMENDED SOLDER STENCIL
TOP VIEW 2



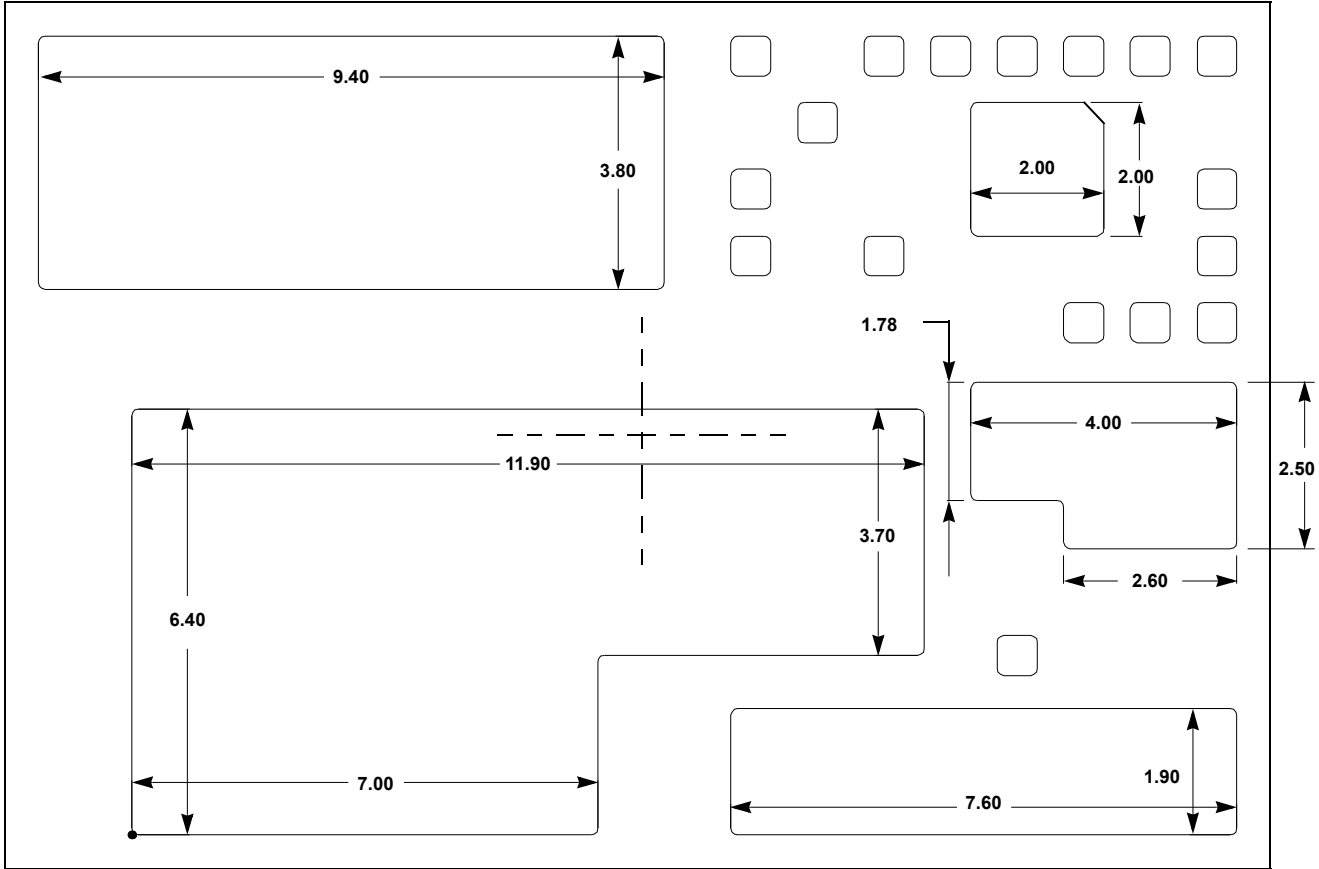
RECOMMENDED POSITIVE SOLDER MASK DEFINED PCB LAND PATTERN

TOP VIEW 1

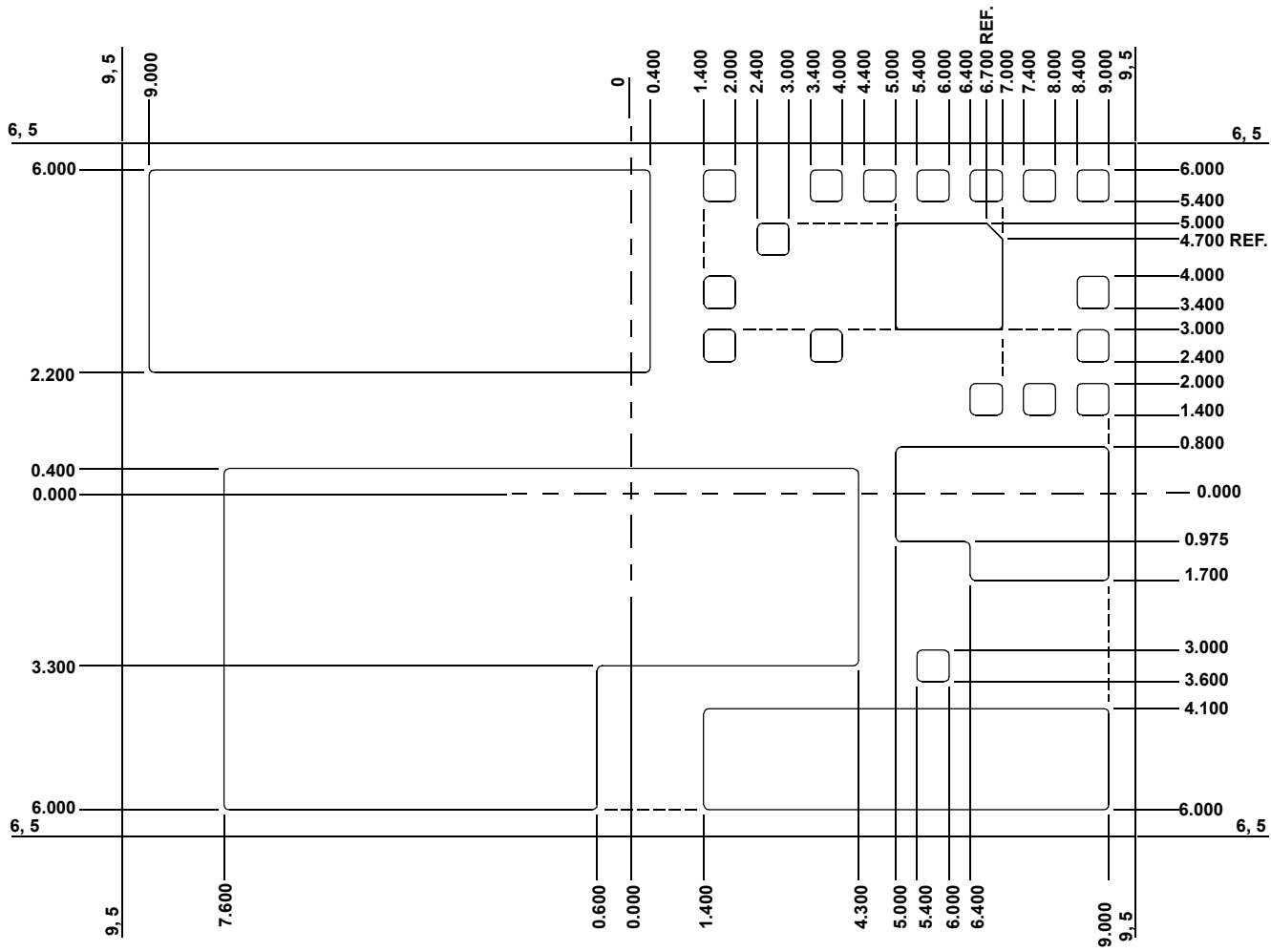


RECOMMENDED POSITIVE SOLDER MASK DEFINED PCB LAND PATTERN

TOP VIEW 2



SIZE DETAILS FOR THE 5 EXPOSED PADS



TERMINAL AND PAD EDGE DETAILS
(BOTTOM VIEW)